Vincotech

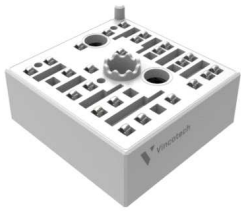
80-M112PMA015M7-K200A70
datasheet

MiniSKiiP® PIM 1 — **1200 V / 15 A**

Features

- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Solder-free spring contact technology
- Built-in PTC

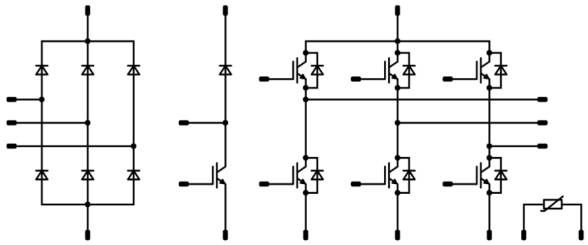
MiniSkiip® 1 housing



Target applications

- Industrial Drives

Schematic



Types

- 80-M112PMA015M7-K200A70

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1600	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	35	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms T_j = 150 °C	200	A
Surge current capability	I^2t		200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	51	W
Maximum Junction Temperature	T_{jmax}		150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	79	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	21	A
Repetitive peak forward current	I_{FRM}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	61	W
Maximum junction temperature	T_{jmax}		175	°C
Brake Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	79	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Brake Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	21	A
Repetitive peak forward current	I_{FRM}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	61	W
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	5500	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance		With std lid For more information see handling instructions	6,3	mm
Clearance		With std lid For more information see handling instructions	6,3	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Rectifier Diode										
Static										
Forward voltage	V_F				25	25 125		1,22 1,21	1,75	V
Reverse leakage current	I_r			1600		25 145			50 1100	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,37		K/W

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	1,95	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		
Reverse transfer capacitance	C_{res}							34		
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,21		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	±15	600	15	25 125 150		196 191 190		ns
Rise time	t_r					25 125 150		60 63 64		
Turn-off delay time	$t_{d(off)}$					25 125 150		181 206 211		
Fall time	t_f					25 125 150		95 113 114		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,5 µC Q_{rFWD} = 2,5 µC Q_{rFWD} = 2,7 µC				25 125 150		1,685 2,106 2,209		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,987 1,327 1,411		

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				15	25 125		1,63 1,74	2,1	V
Reverse leakage current	I_R			1200		25			30	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,55		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 181 A/µs di/dt = 205 A/µs di/dt = 175 A/µs	±15	600	15	25 125 150		9 11 11		A
Reverse recovery time	t_{rr}					25 125 150		286 422 471		ns
Recovered charge	Q_r					25 125 150		1,496 2,463 2,684		µC
Reverse recovered energy	E_{rec}					25 125 150		0,497 0,913 1,000		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		77 49 44		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	1,95	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		
Reverse transfer capacitance	C_{res}							34		
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,21		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	15/0	600	15	25 125 150		96 85 78		ns
Rise time	t_r					25 125 150		61 62 65		
Turn-off delay time	$t_{d(off)}$					25 125 150		296 324 331		
Fall time	t_f					25 125 150		97 116 120		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,5 µC Q_{rFWD} = 2,4 µC Q_{rFWD} = 2,7 µC				25 125 150		1,647 2,054 2,173		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		1,004 1,340 1,428		

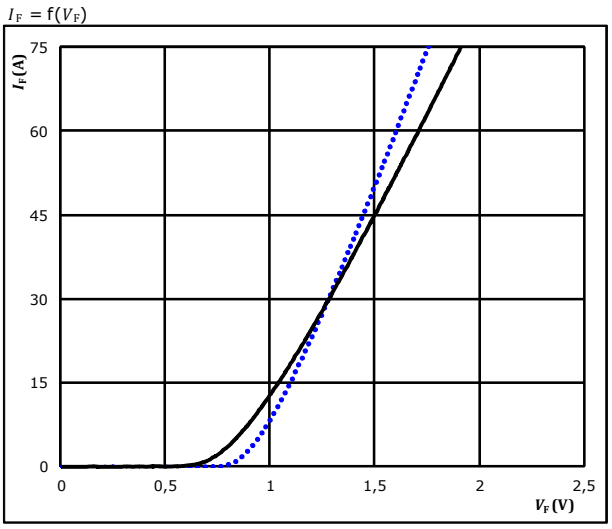
Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Diode										
Static										
Forward voltage	V_F				15	25 125		1,63 1,74	2,1	V
Reverse leakage current	I_R			1200		25			30	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 2,5 W/mK (HPTP)						1,55		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 205 A/µs di/dt = 185 A/µs di/dt = 188 A/µs	15/0	600	15	25 125 150		10 11 11		A
Reverse recovery time	t_{rr}					25 125 150		283 420 463		ns
Recovered charge	Q_r					25 125 150		1,486 2,440 2,680		µC
Reverse recovered energy	E_{rec}					25 125 150		0,505 0,916 1,009		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		75 51 47		A/µs
Thermistor										
Rated resistance	R					25		1		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1670 Ω				100	-2		+2	%
R_{100}	R					100		1670		Ω
Power dissipation constant						25		0,76		mW/K
A-value	$A_{(25/50)}$					25		$7,635*10^{-3}$		1/K
B-value	$B_{(25/100)}$					25		$1,731*10^{-5}$		1/K²
Vincotech PTC Reference									E	

Rectifier Diode Characteristics

figure 1. **FWD**

Typical forward characteristics



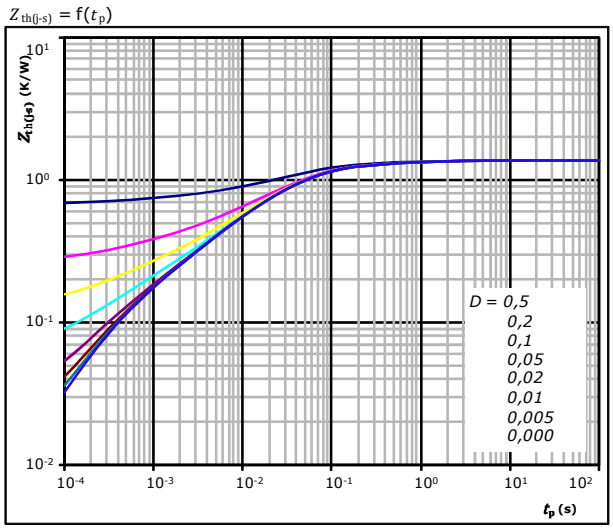
t_p = 250 µs

T_j: 25 °C

T_j: 125 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width



D = t_p / T

$R_{th(j-s)}$ = 1,37 K/W

Diode thermal model values

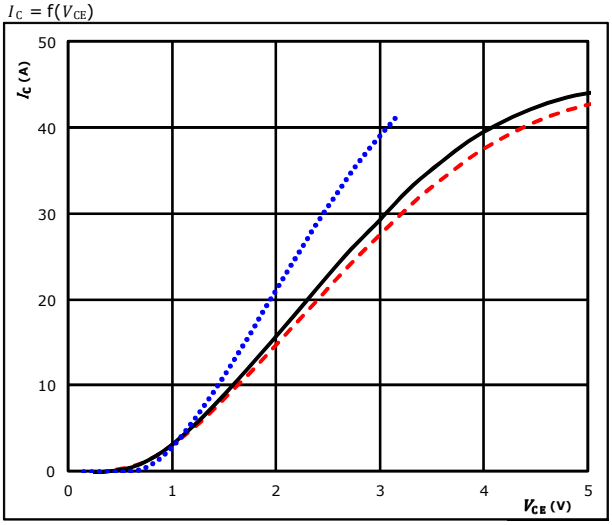
R (K/W)	τ (s)
6,75E-02	1,56E+00
1,34E-01	2,41E-01
6,34E-01	4,40E-02
3,25E-01	9,85E-03
1,24E-01	2,12E-03
8,72E-02	3,56E-04
8,72E-02	3,56E-04

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

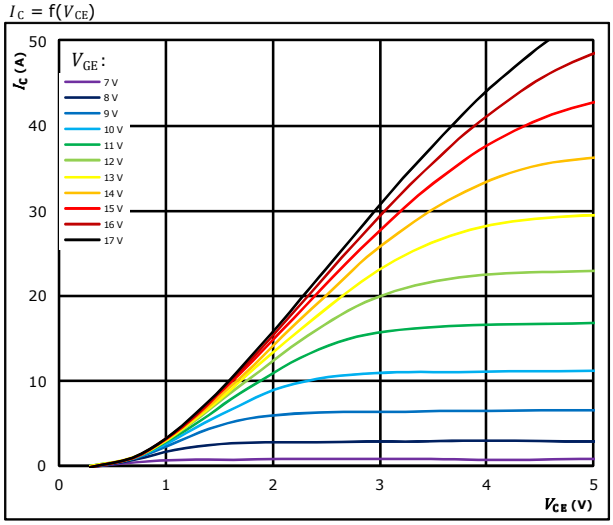


t_p =	250	µs		25 °C
V_{GE} =	15	V	T_j:	125 °C
				150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

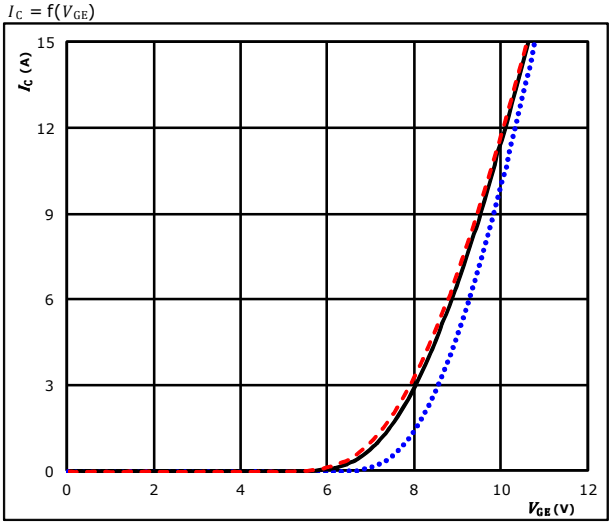


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

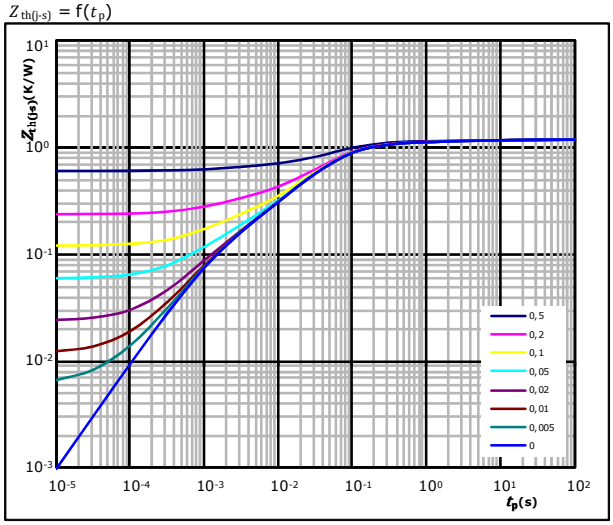


t_p =	100	µs		25 °C
V_{CE} =	10	V	T_j:	125 °C
				150 °C

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,21	K/W

IGBT thermal model values

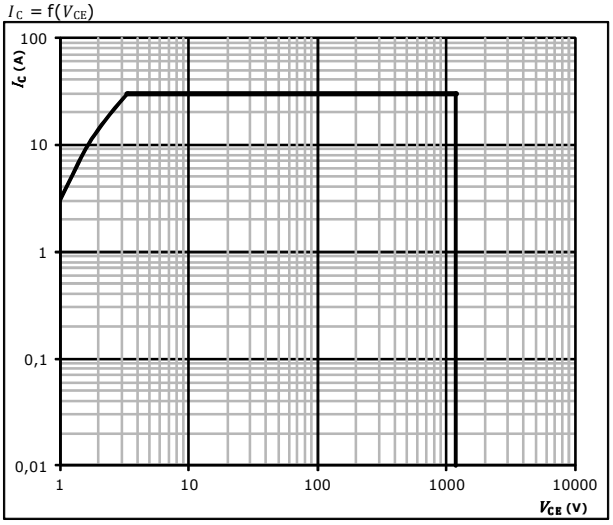
R (K/W)	τ (s)
4,50E-02	9,01E+00
8,43E-02	7,67E-01
2,24E-01	1,37E-01
6,47E-01	4,58E-02
1,21E-01	8,90E-03
8,10E-02	1,37E-03
5,58E-03	6,60E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



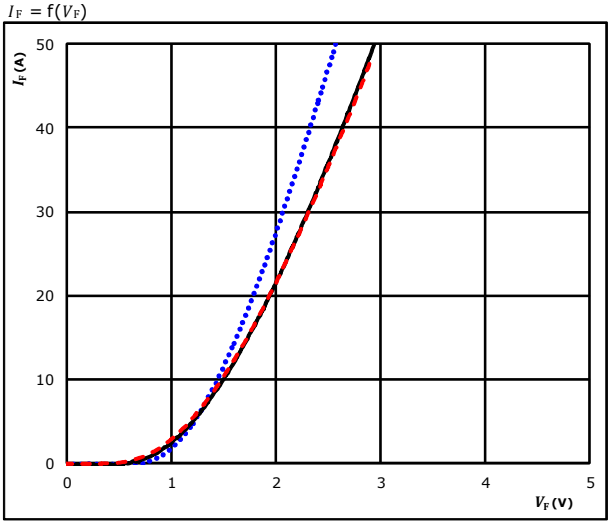
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



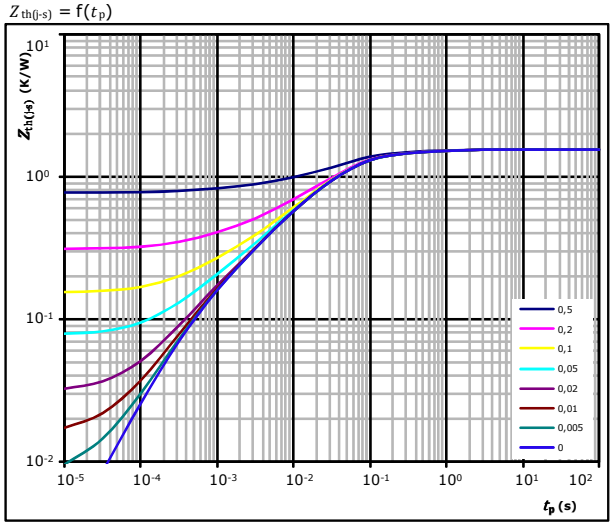
t_p = 250 µs

T_j: 25 °C
125 °C
150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,55 K/W

FWD thermal model values

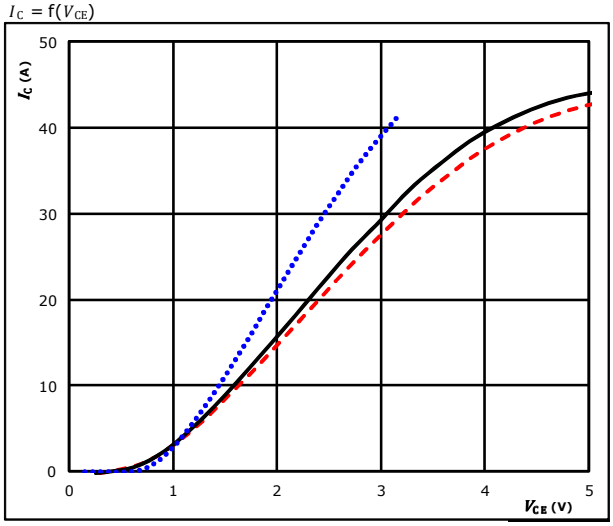
R (K/W)	τ (s)
8,07E-02	1,12E+00
2,22E-01	1,47E-01
8,07E-01	3,59E-02
2,86E-01	6,71E-03
9,51E-02	1,49E-03
5,83E-02	3,63E-04

Brake Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

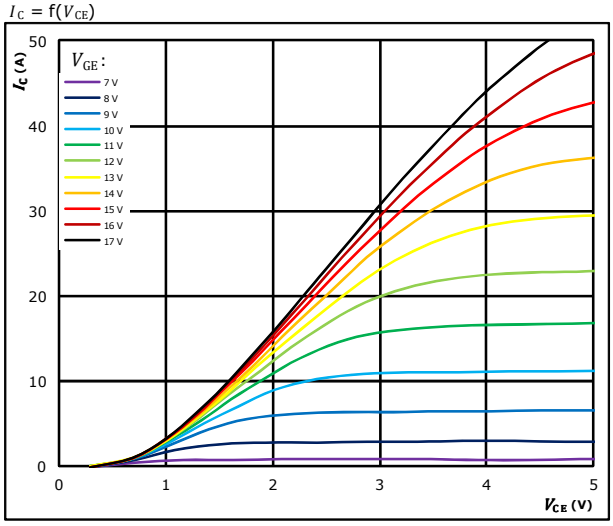


t_p =	250	µs		25 °C
V_{GE} =	15	V	T_j:	125 °C
				150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

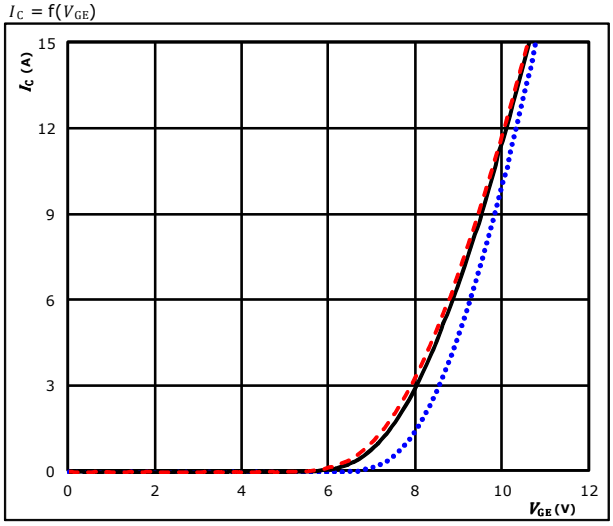


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

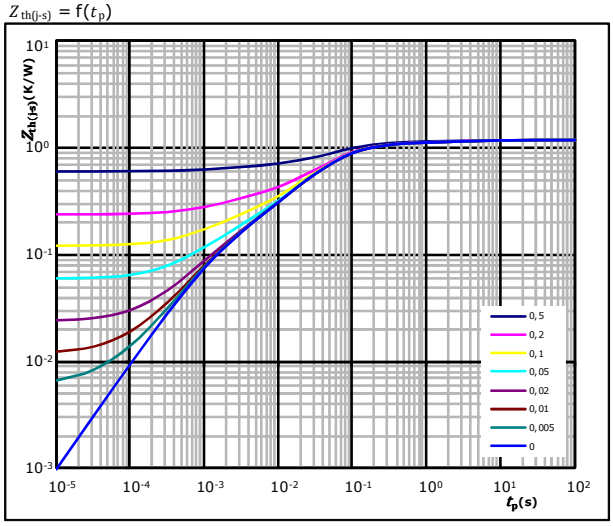


t_p =	100	µs		25 °C
V_{CE} =	10	V	T_j:	125 °C
				150 °C

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,21	K/W

IGBT thermal model values

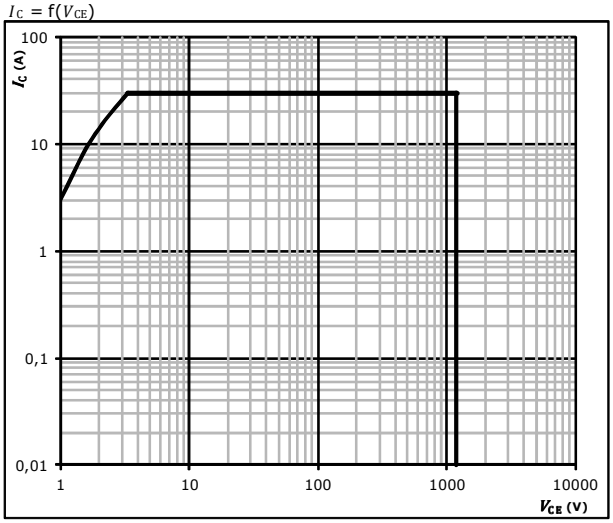
R (K/W)	τ (s)
4,50E-02	9,01E+00
8,43E-02	7,67E-01
2,24E-01	1,37E-01
6,47E-01	4,58E-02
1,21E-01	8,90E-03
8,10E-02	1,37E-03
5,58E-03	6,60E-04

Brake Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



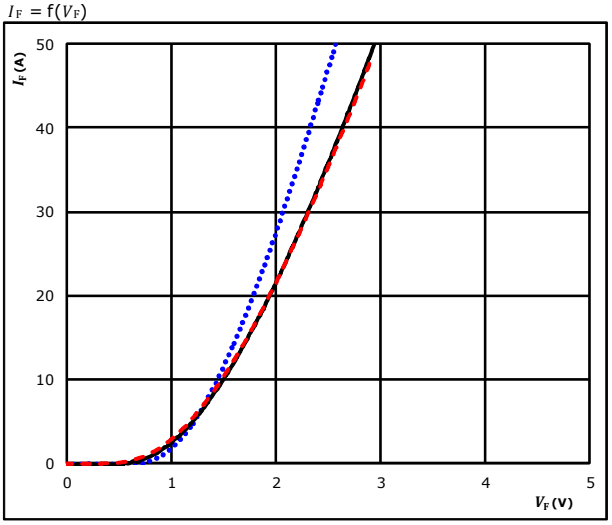
D =	single pulse	
T_s =	80	°C
V_{GE} =	±15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



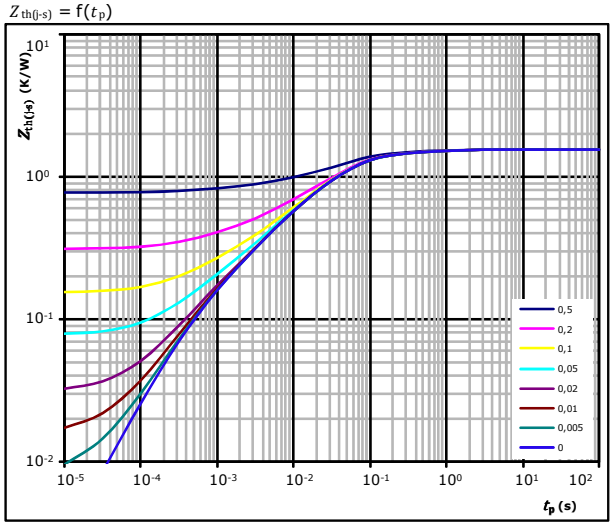
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,55 K/W

FWD thermal model values

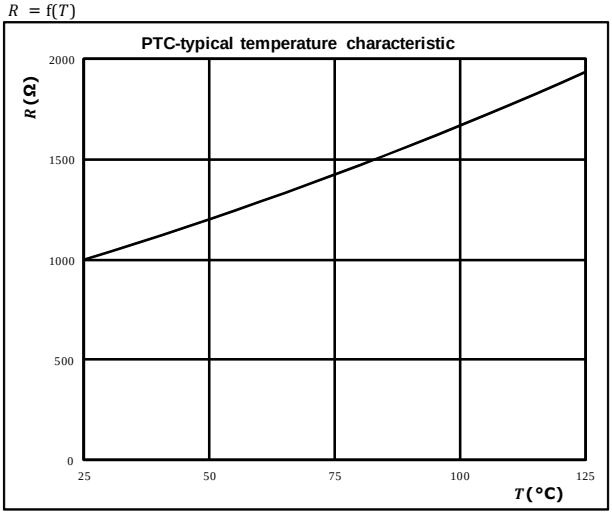
R (K/W)	τ (s)
8,07E-02	1,12E+00
2,22E-01	1,47E-01
8,07E-01	3,59E-02
2,86E-01	6,71E-03
9,51E-02	1,49E-03
5,83E-02	3,63E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical PTC characteristic
as a function of temperature

$R = f(T)$

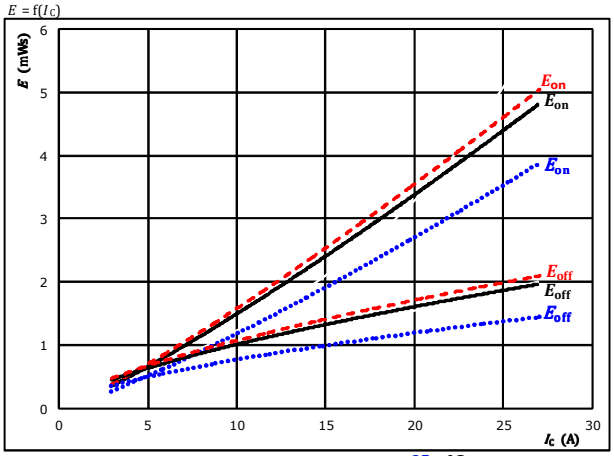


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



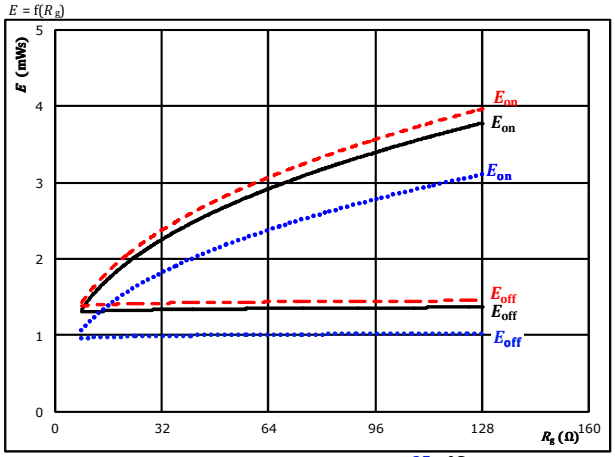
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
R_{gon} =	32	Ω		150 °C	– – –
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



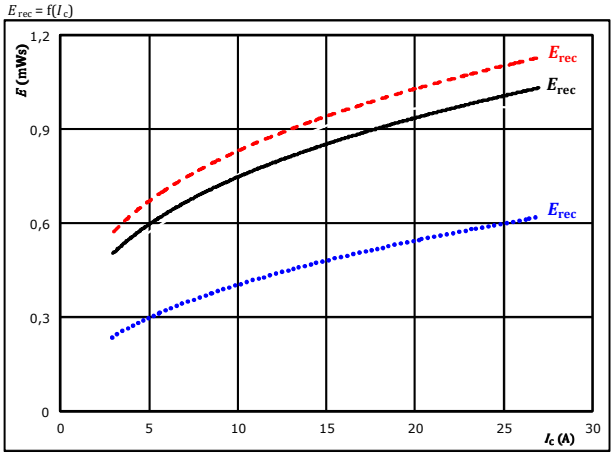
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
I_C =	15	A		150 °C	– – –

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



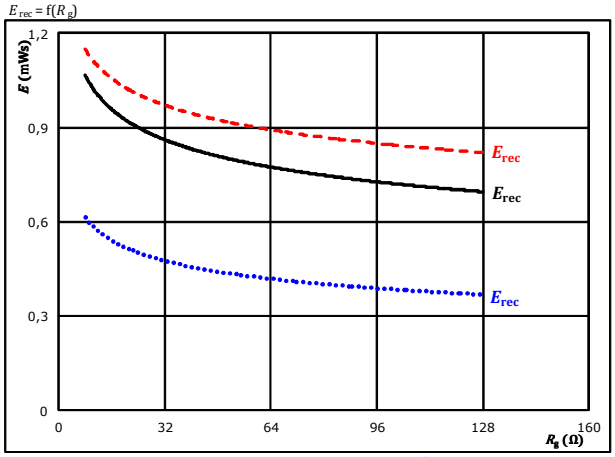
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
R_{gon} =	32	Ω		150 °C	– – –

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

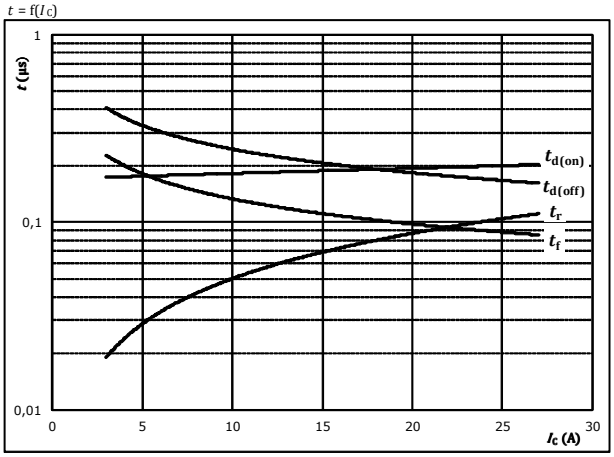
V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
I_C =	15	A		150 °C	– – –

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



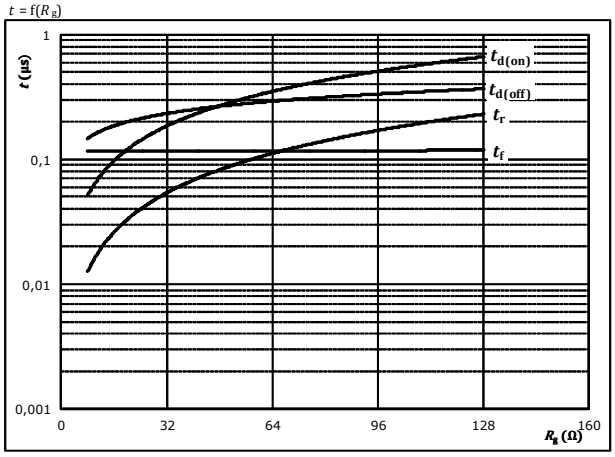
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



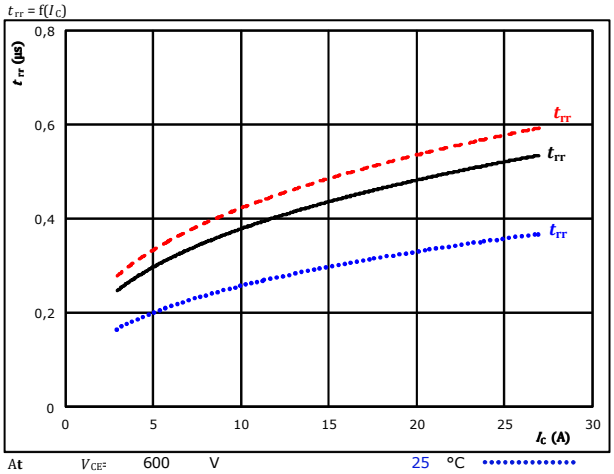
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

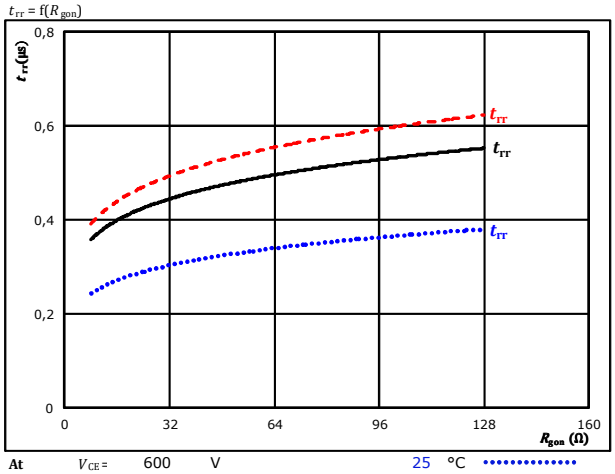


At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
R_{gon} =	32	Ω		150	°C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



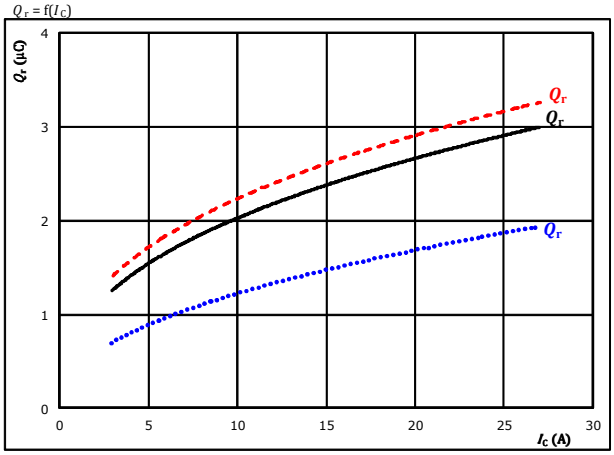
At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
I_C =	15	A		150	°C

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

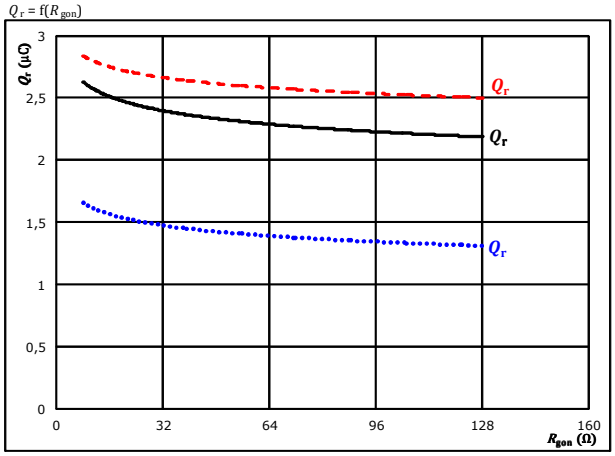


At	V_{CE} =	600	V		25 °C	•••••••••••••••
	V_{GE} =	±15	V	T_j:	125 °C	———
	R_{gon} =	32	Ω		150 °C	– – – –

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

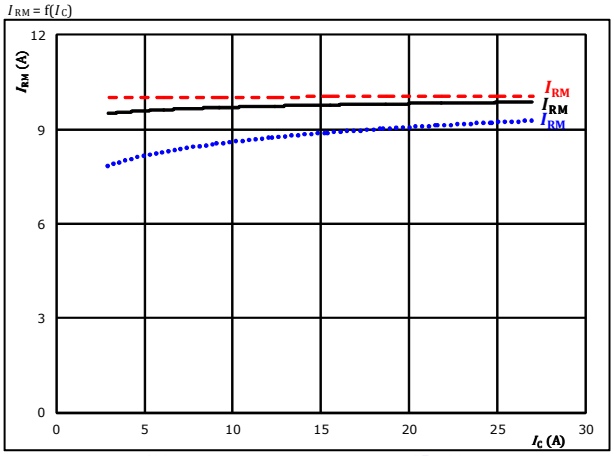


At	V_{CE}=	600	V		25 °C	•••••••••••••••
	V_{GE} =	±15	V	T_j:	125 °C	———
	I_C=	15	A		150 °C	– – – –

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

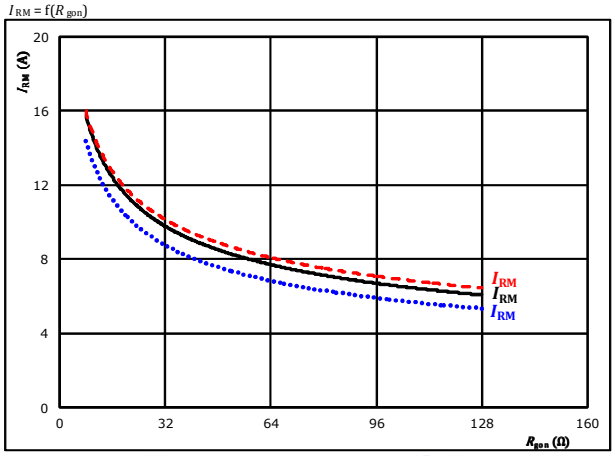


At	V_{CE}:	600	V		25 °C	•••••••••••••••
	V_{GE} =	±15	V	T_j:	125 °C	———
	R_{gon} =	32	Ω		150 °C	– – – –

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



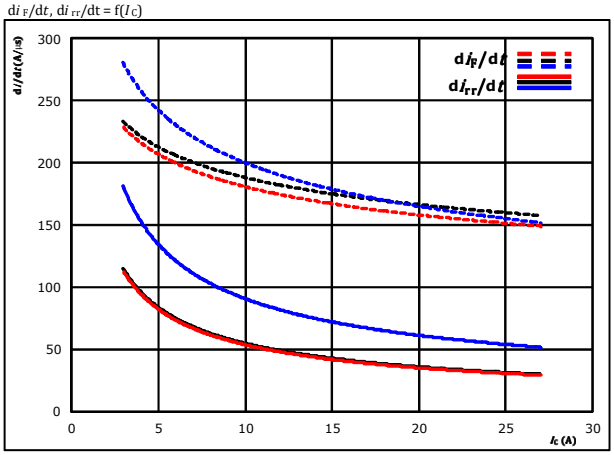
At	V_{CE} =	600	V		25 °C	•••••••••••••••
	V_{GE} =	±15	V	T_j:	125 °C	———
	I_C =	15	A		150 °C	– – – –

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

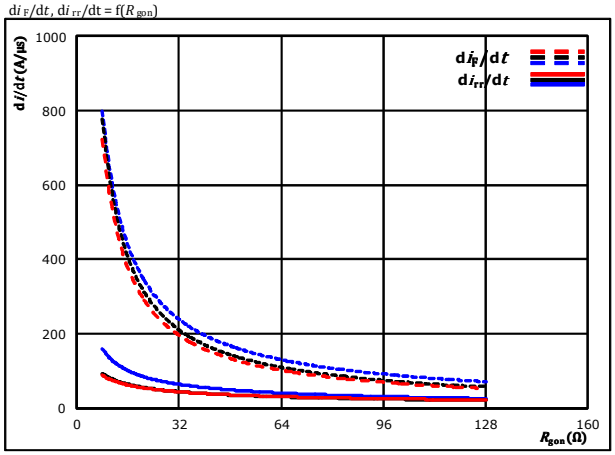


At					
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	32	Ω		150 °C	

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_{gon})$

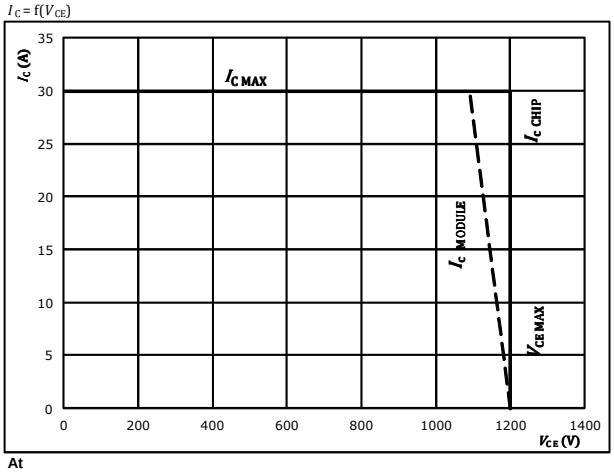


At					
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	15	A		150 °C	

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

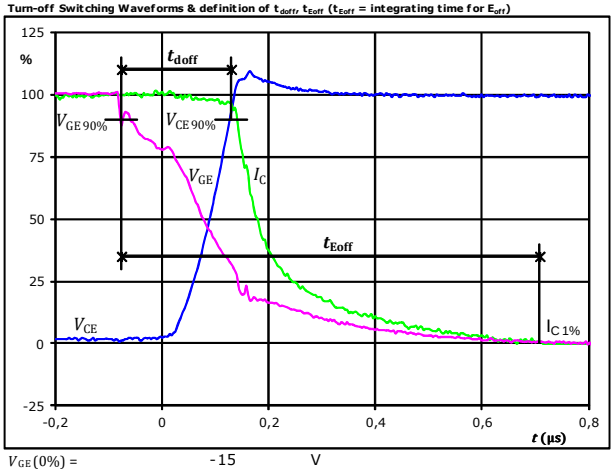
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

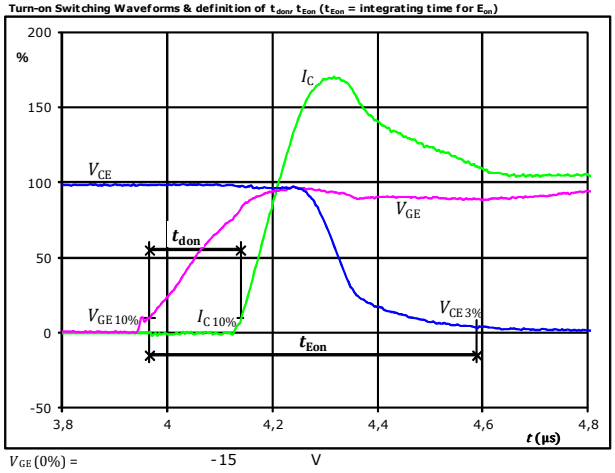
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{doff} =	0,206	µs
t_{Eoff} =	0,784	µs

figure 2. IGBT

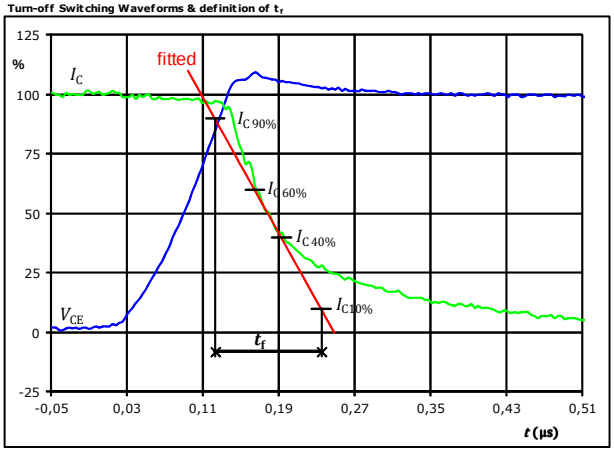
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{don} =	0,191	µs
t_{Eon} =	0,623	µs

figure 3. IGBT

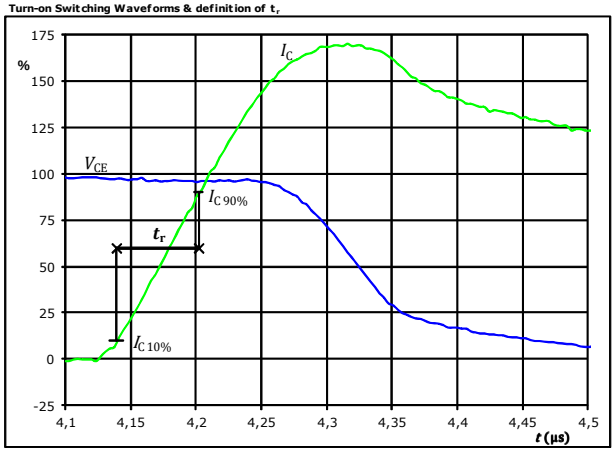
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_f =	0,113	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

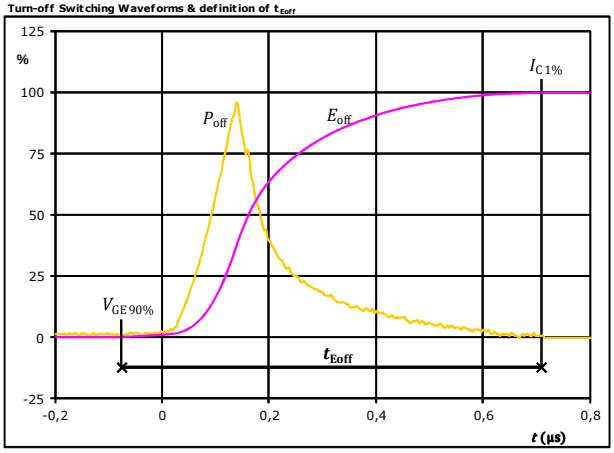


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_r =	0,063	µs

Inverter Switching Characteristics

figure 5. **IGBT**

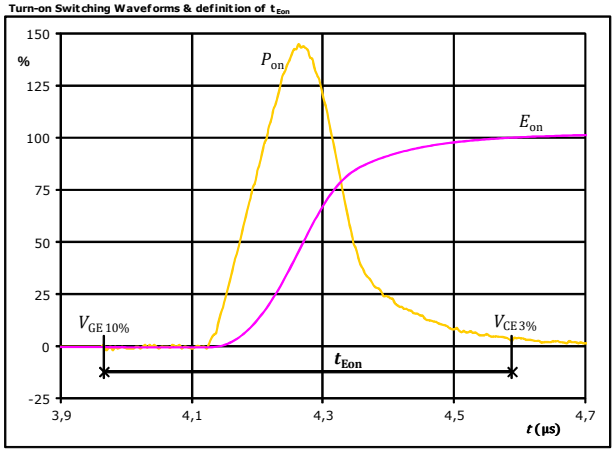
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	9,01	kW
$E_{off}(100\%)$ =	1,33	mJ
t_{Eoff} =	0,78	µs

figure 6. **IGBT**

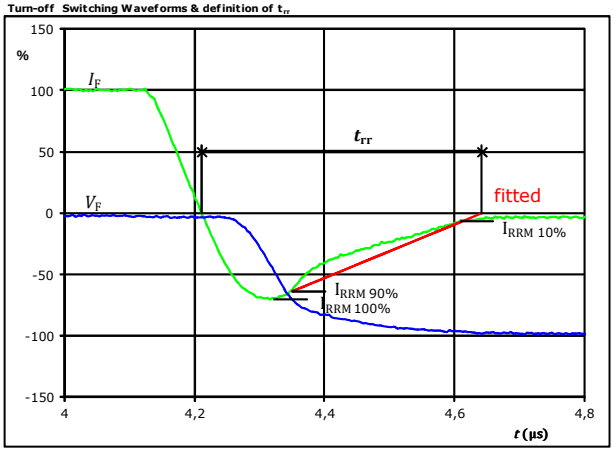
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	9,01	kW
$E_{on}(100\%)$ =	2,11	mJ
t_{Eon} =	0,62	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

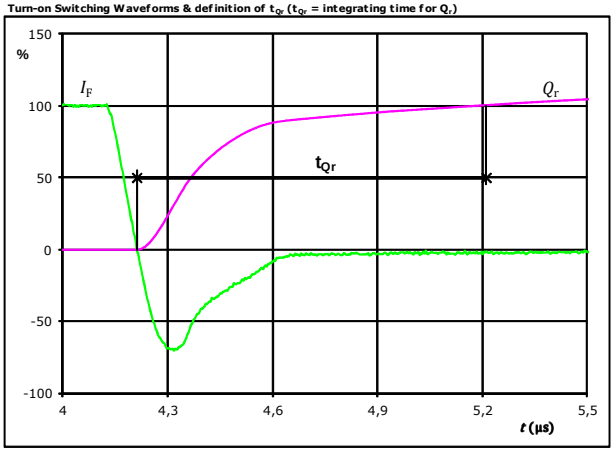


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	15	A
$I_{RRM}(100\%)$ =	-11	A
t_{rr} =	0,422	µs

Inverter Switching Characteristics

figure 8. **FWD**

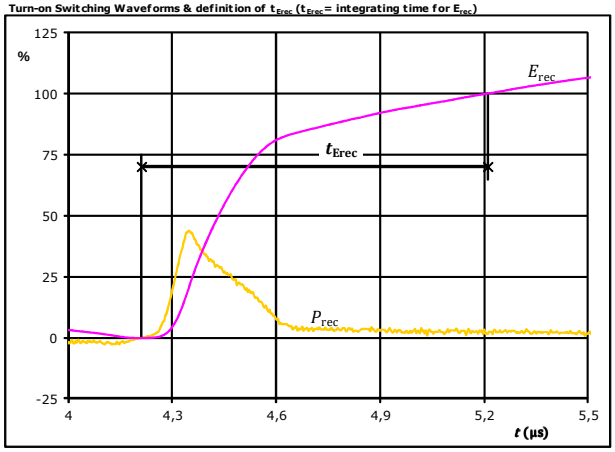
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	15	A
Q_r (100%) =	2,46	µC
t_{Qr} =	1,00	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



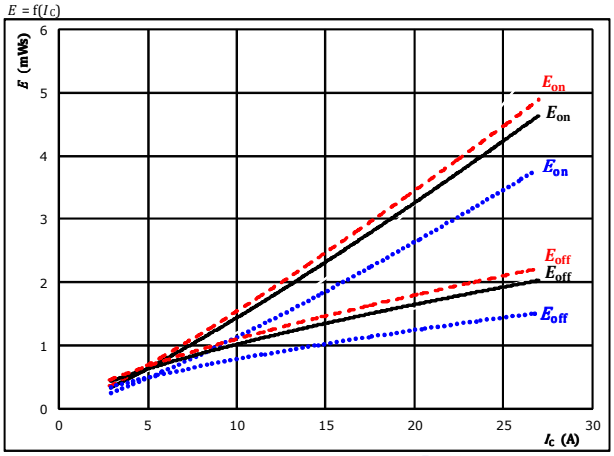
P_{rec} (100%) =	9,01	kW
E_{rec} (100%) =	0,91	mJ
t_{Erec} =	1,00	µs

Brake Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



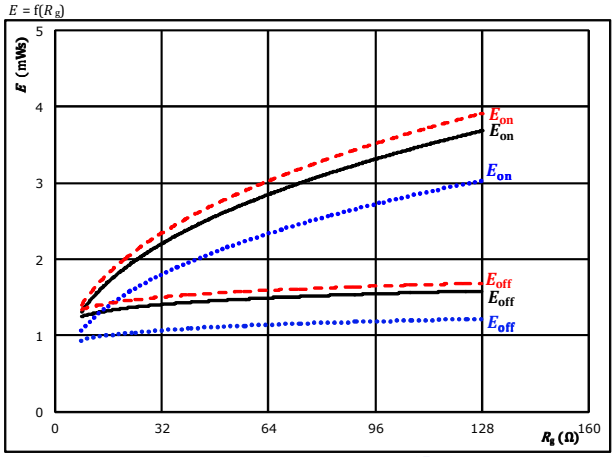
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	15/0	V		125 °C	———
R_{gon} =	32	Ω		150 °C	- - -
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



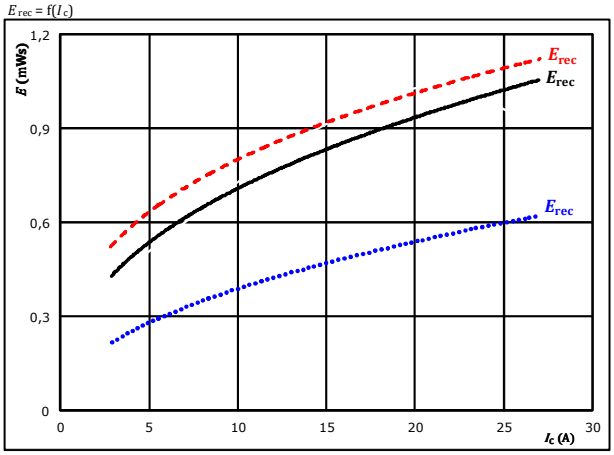
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	15/0	V		125 °C	———
I_C =	15	A		150 °C	- - -

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



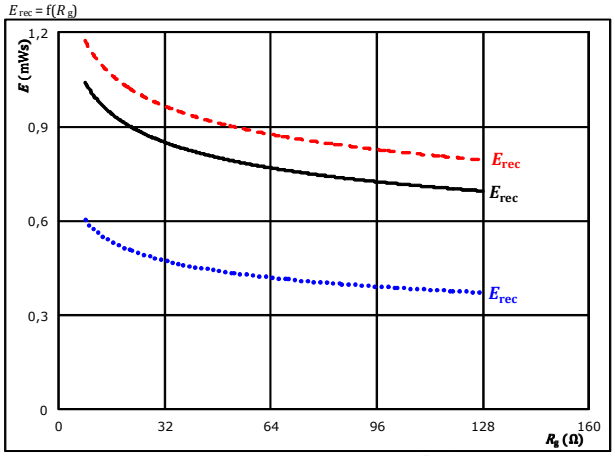
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	15/0	V		125 °C	———
R_{gon} =	32	Ω		150 °C	- - -

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

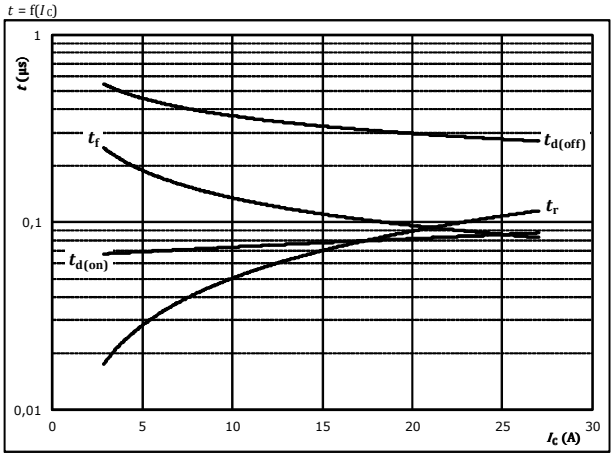
V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	15/0	V		125 °C	———
I_C =	15	A		150 °C	- - -

Brake Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



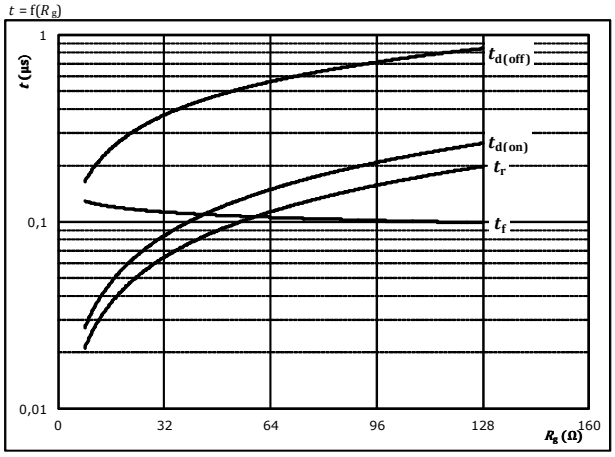
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	15/0	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



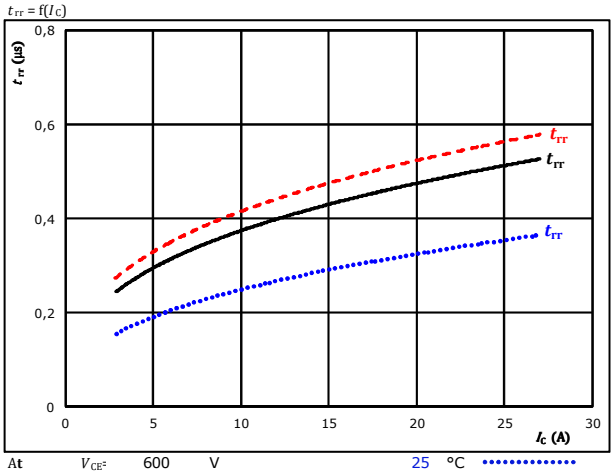
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	15/0	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

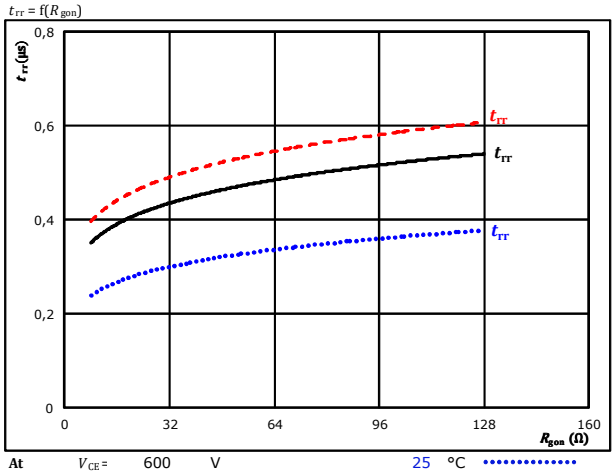


At	V_{CE} =	600	V	T_j:	25 °C
	V_{GE} =	15/0	V		125 °C
	R_{gon} =	32	Ω		150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



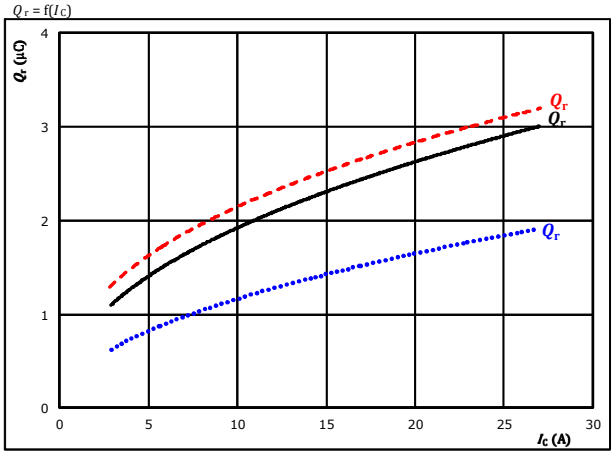
At	V_{CE} =	600	V	T_j:	25 °C
	V_{GE} =	15/0	V		125 °C
	I_C =	15	A		150 °C

Brake Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

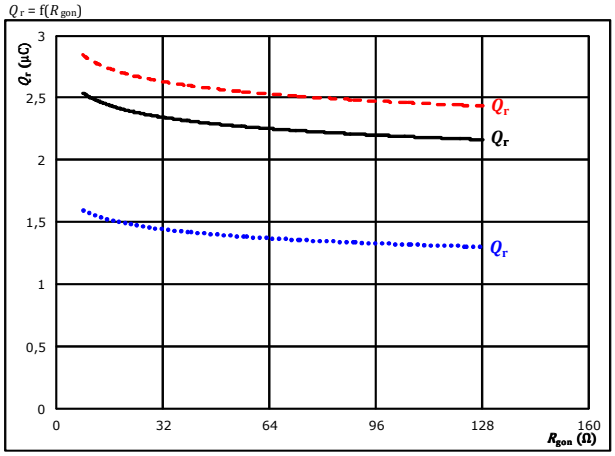


At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	15/0	V	T_j:	125 °C	
	R_{gon} =	32	Ω		150 °C	

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

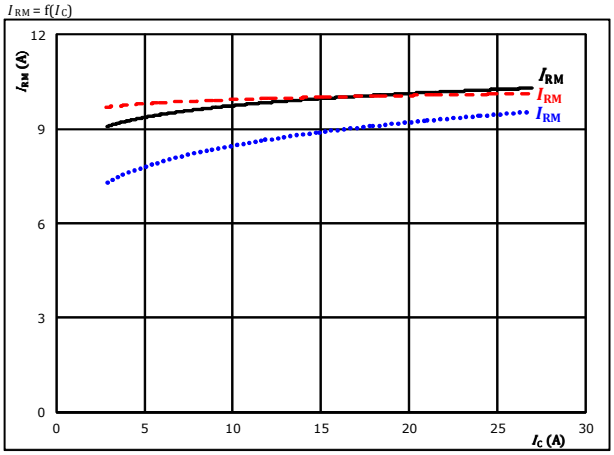


At						
	V_{CE}=	600	V		25 °C	
	V_{GE} =	15/0	V	T_j:	125 °C	
	I_C=	15	A		150 °C	

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

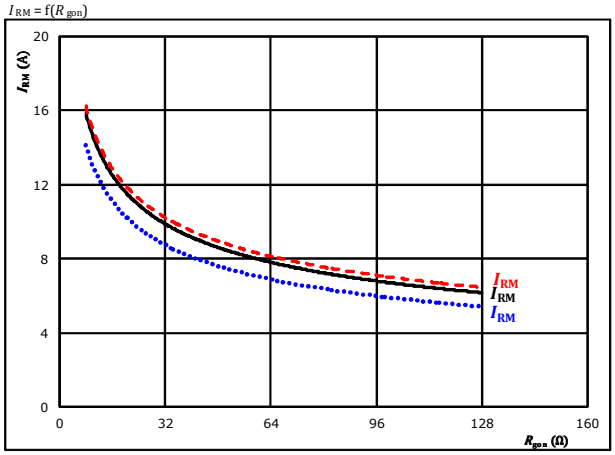


At						
	V_{CE}:	600	V		25 °C	
	V_{GE} =	15/0	V	T_j:	125 °C	
	R_{gon} =	32	Ω		150 °C	

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



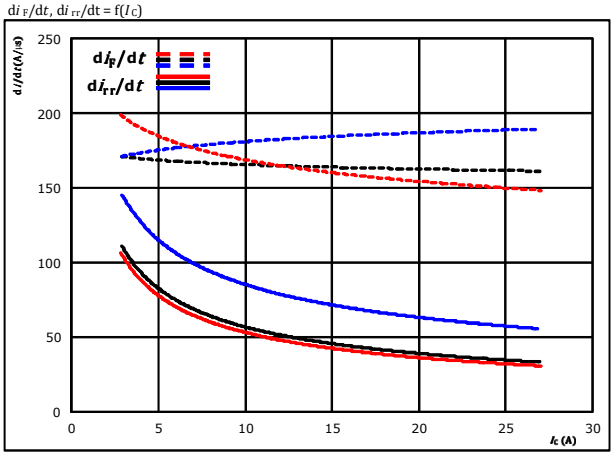
At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	15/0	V	T_j:	125 °C	
	I_C =	15	A		150 °C	

Brake Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

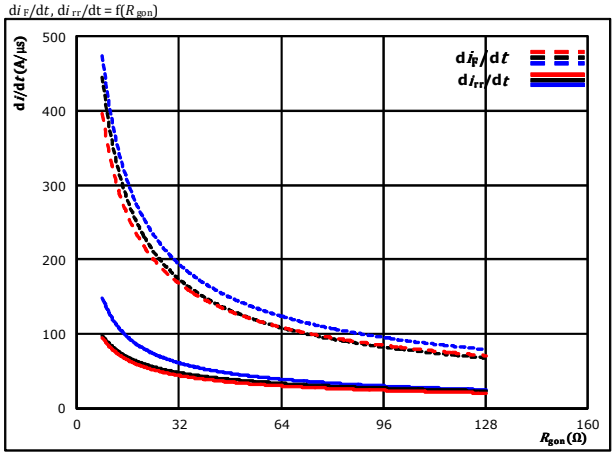


At						
V_{CE} =	600	V	T_j:	25 °C	•••••••••••••••
V_{GE} =	15/0	V		125 °C	———
R_{gon} =	32	Ω		150 °C	- - - -

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

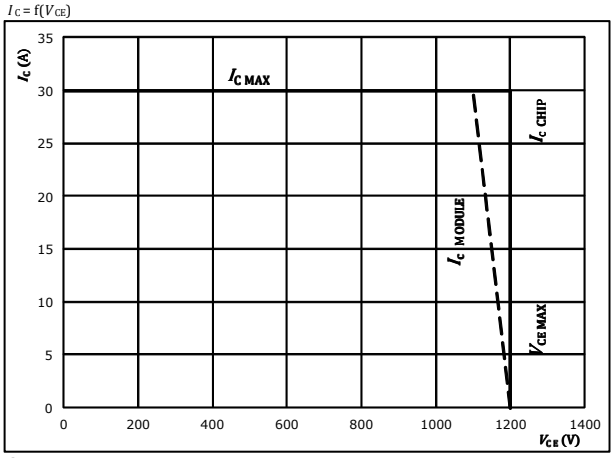


At						
V_{CE} =	600	V	T_j:	25 °C	•••••••••••••••
V_{GE} =	15/0	V		125 °C	———
I_C =	15	A		150 °C	- - - -

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

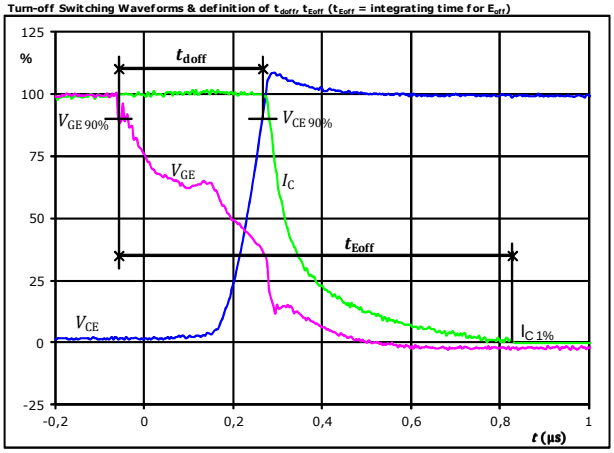
Brake Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

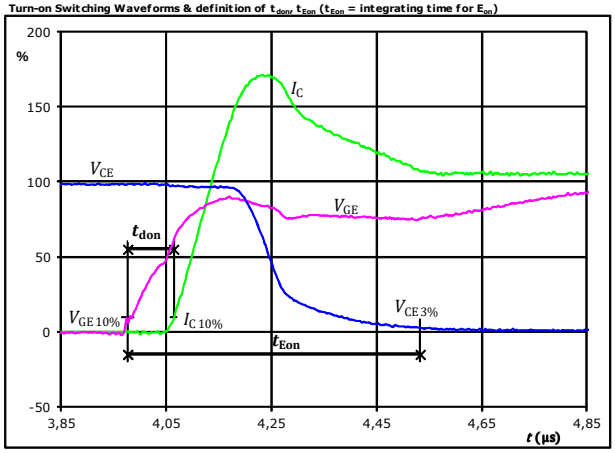
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{doff} =	0,324	µs
t_{Eoff} =	0,885	µs

figure 2. IGBT

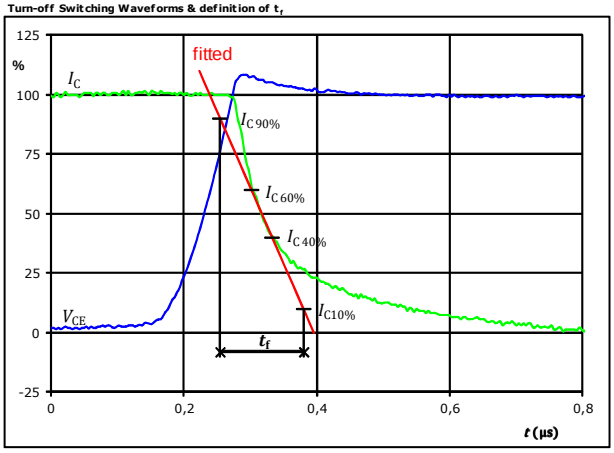
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{don} =	0,085	µs
t_{Eon} =	0,556	µs

figure 3. IGBT

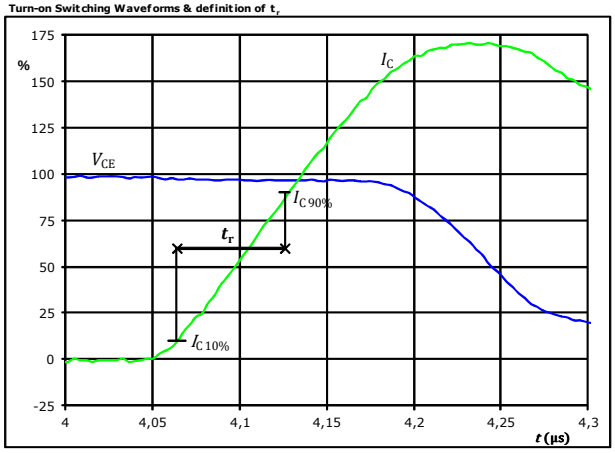
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_f =	0,116	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

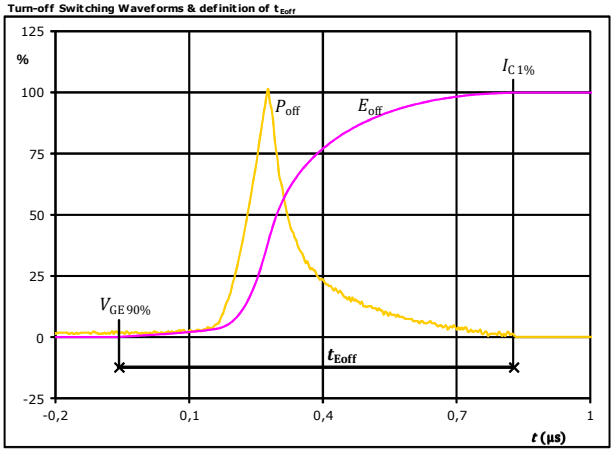


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_r =	0,062	µs

Brake Switching Characteristics

figure 5. **IGBT**

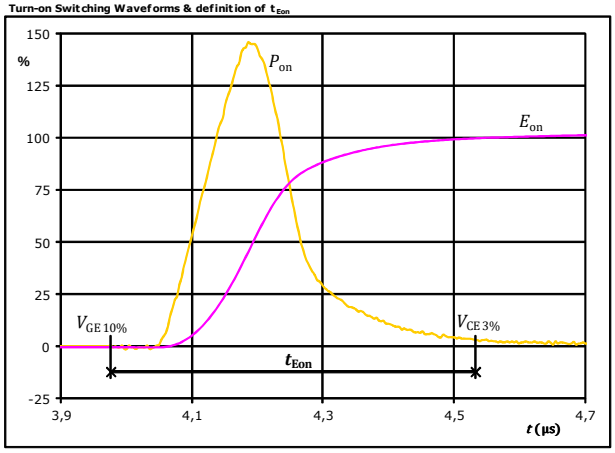
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	8,99	kW
$E_{off}(100\%)$ =	1,34	mJ
t_{Eoff} =	0,89	µs

figure 6. **IGBT**

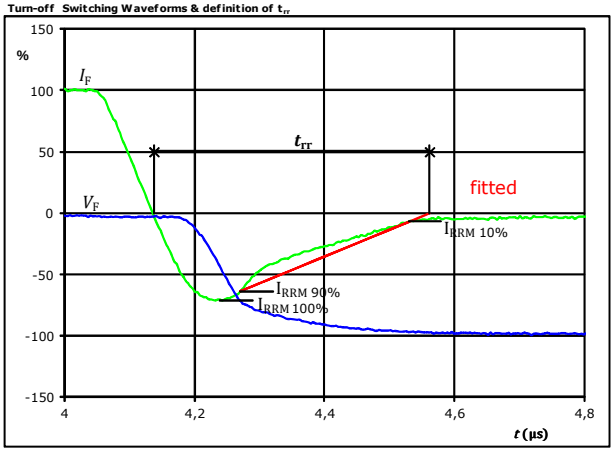
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	8,99	kW
$E_{on}(100\%)$ =	2,05	mJ
t_{Eon} =	0,56	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

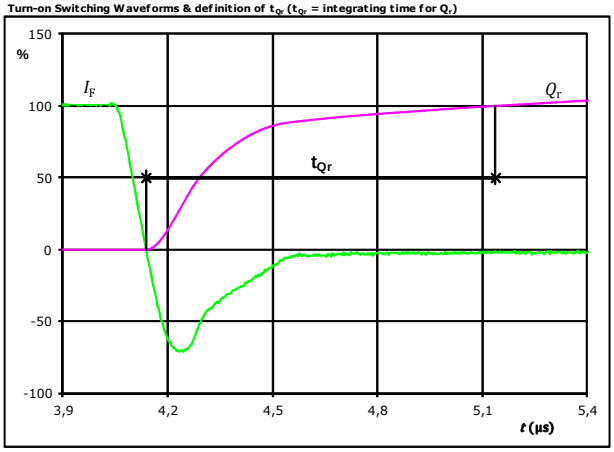


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	15	A
$I_{RRM}(100\%)$ =	-11	A
t_{rr} =	0,420	µs

Brake Switching Characteristics

figure 8. **FWD**

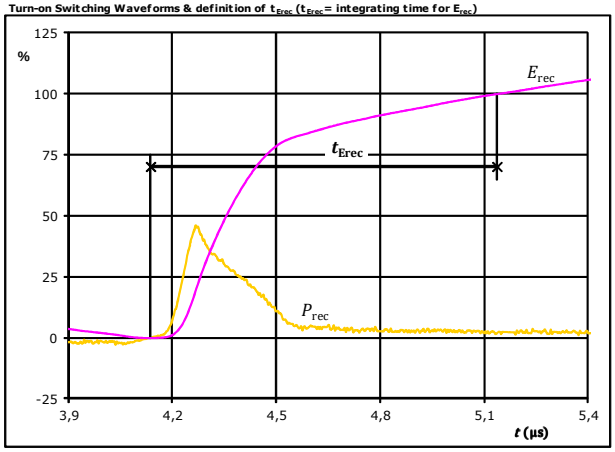
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	15	A
Q_r (100%) =	2,44	µC
t_{Qr} =	1,00	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	8,99	kW
E_{rec} (100%) =	0,92	mJ
t_{Erec} =	1,00	µs

Vincotech

Ordering Code & Marking

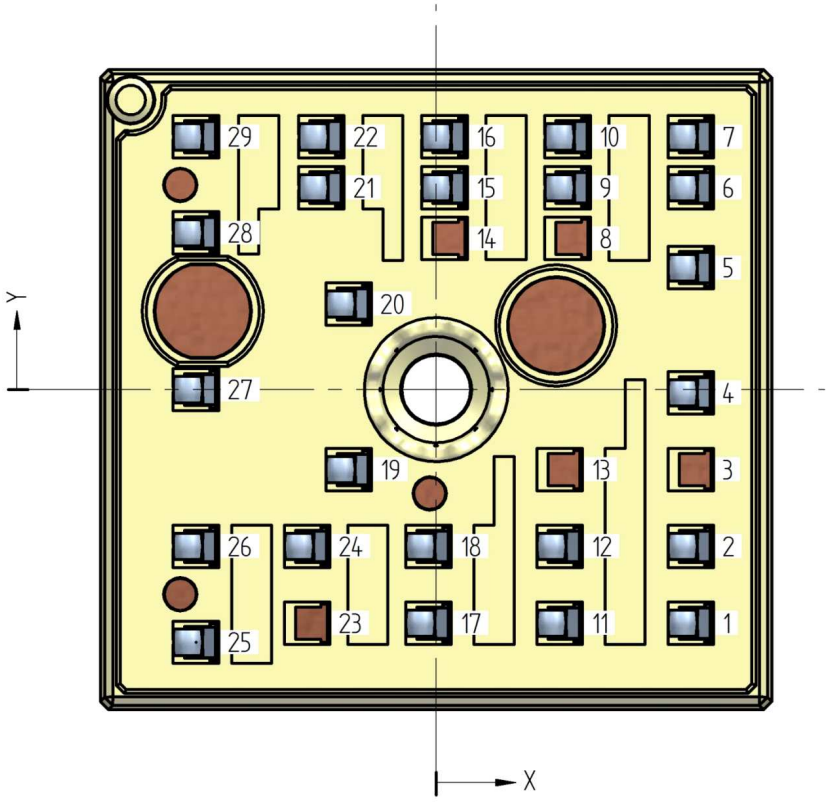
Version	Ordering Code
With std lid (6.5mm height) + no thermal grease	80-M112PMA015M7-K200A70-/0A/
With thin lid (2.8mm height) + no thermal grease	80-M112PMA015M7-K200A70-/0B/
With std lid (6.5mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M112PMA015M7-K200A70-/1A/
With thin lid (2.8mm height) + thermal grease (0,8 W/mK, P12, silicone-based)	80-M112PMA015M7-K200A70-/1B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M112PMA015M7-K200A70-/4A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, TG20032, silicone-free)	80-M112PMA015M7-K200A70-/4B/
With std lid (6.5mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M112PMA015M7-K200A70-/5A/
With thin lid (2.8mm height) + thermal grease (2,5 W/mK, HPTP, silicone-based)	80-M112PMA015M7-K200A70-/5B/

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTVV	LLLLL	SSSS	WWYY		

Outline

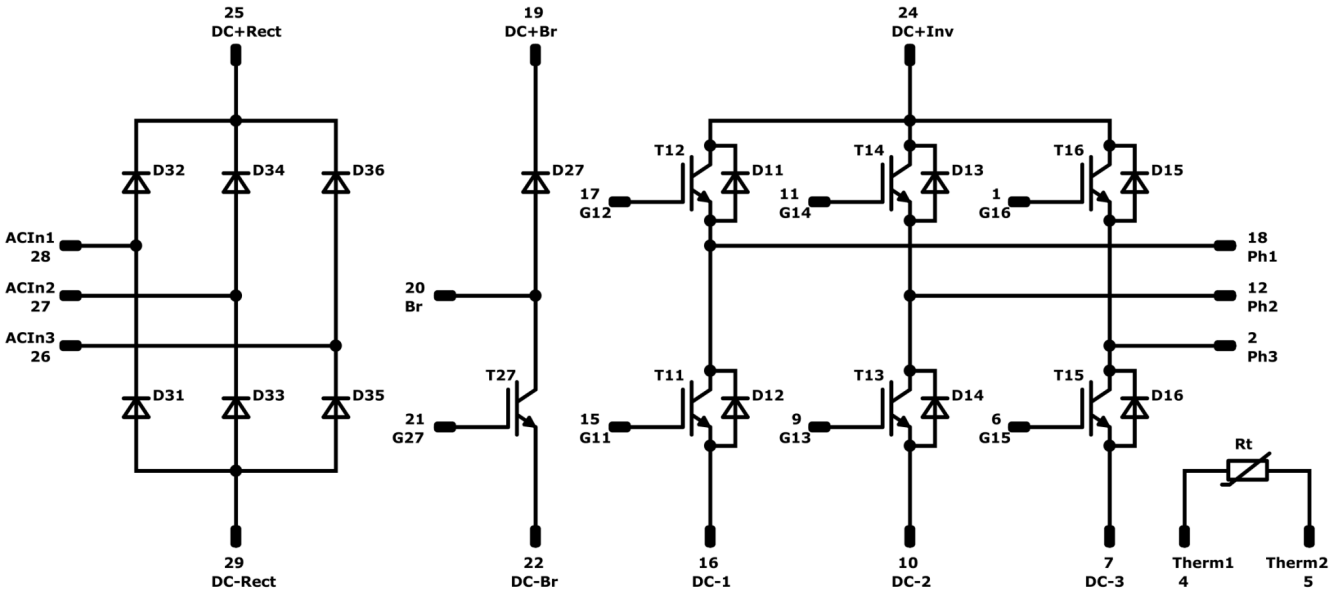
PCB pad table

Pin	X	Y	Function
1	15,93	-14,6	G16
2	15,93	-9,8	Ph3
3	Not assembled		
4	15,93	-0,2	Therm1
5	15,93	7,62	Therm2
6	15,93	12,62	G15
7	15,93	15,8	DC-3
8	Not assembled		
9	8,23	12,62	G13
10	8,23	15,8	DC-2
11	7,73	-14,6	G14
12	7,73	-9,8	Ph2
13	Not assembled		
14	Not assembled		
15	0,53	12,62	G11
16	0,53	15,8	DC-1
17	-0,47	-14,6	G12
18	-0,47	-9,8	Ph1
19	-5,47	-5	DC+Br
20	-5,47	5,35	Br
21	-7,17	12,62	G27
22	-7,17	15,8	DC-Br
23	Not assembled		
24	-8,07	-9,8	DC+Inv
25	-15,02	-15,8	DC+Rect
26	-15,02	-9,8	ACIn3
27	-15,02	0	ACIn2
28	-15,02	9,8	ACIn1
29	-15,02	15,8	DC-Rect



Pad positions refers to center point. For more informations on pad design please see package data

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
D31-D36	Rectifier	1600 V	25 A	Rectifier Diode	
T11-T16	IGBT	1200 V	15 A	Inverter Switch	
D11-D16	FWD	1200 V	15 A	Inverter Diode	
T27	IGBT	1200 V	15 A	Brake Switch	
D27	FWD	1200 V	15 A	Brake Diode	
Rt	PTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 120	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for MiniSkiiP® 1 packages see vincotech.com website.

Package data
Package data for MiniSkiiP® 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
80-M112PMA015M7-K200A70-D2-14	11 Jan. 2018		